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(54) **ELECTRONIC CIRCUIT DEVICE AND  
MANUFACTURE THEREOF**

(57) Abstract:

PURPOSE: To enable a problem of realization of high density and reliability of electrical connection between circuit elements to be solved when constituting an electronic circuit by performing solder-connection of the circuit elements to a conventional printed-wiring board and then provide for an electronic circuit device which is superb in realization of high density of the circuit and reliability of electrical connection between the circuit elements in the electronic circuit device which is used for a wide range of electronic equipment.

CONSTITUTION: Various kinds of circuit elements 5 and 6 constituting an electronic circuit are buried at a specified position of an insulation resin 7 and external connection terminal layers 5a and 6a of the circuit elements 5 and 6 which are exposed at one portion of the surface are electrically connected by a wiring circuit conductor layer 8 and then the circuit elements 5 and 6 are directly connected by the wiring circuit conductor layer 8 electrically, thus enabling a high-density circuit to be constituted as compared with a solder connection method and at the same time obtaining an

effect for improving reliability in connection between the circuit elements since no solder connection is required.

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